

NOT „MAKE OR BUY“ BUT „**BUY AND MAKE**“

WHY BETTER DESIGN **WITH A SOM**
INSTEAD OF AN ONBOARD CPU

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DESIGN AUTOMATION & EMBEDDED SYSTEMS

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THE MAGIC TRIANGLE OF PROJECT-/PRODUCTMANAGEMENT



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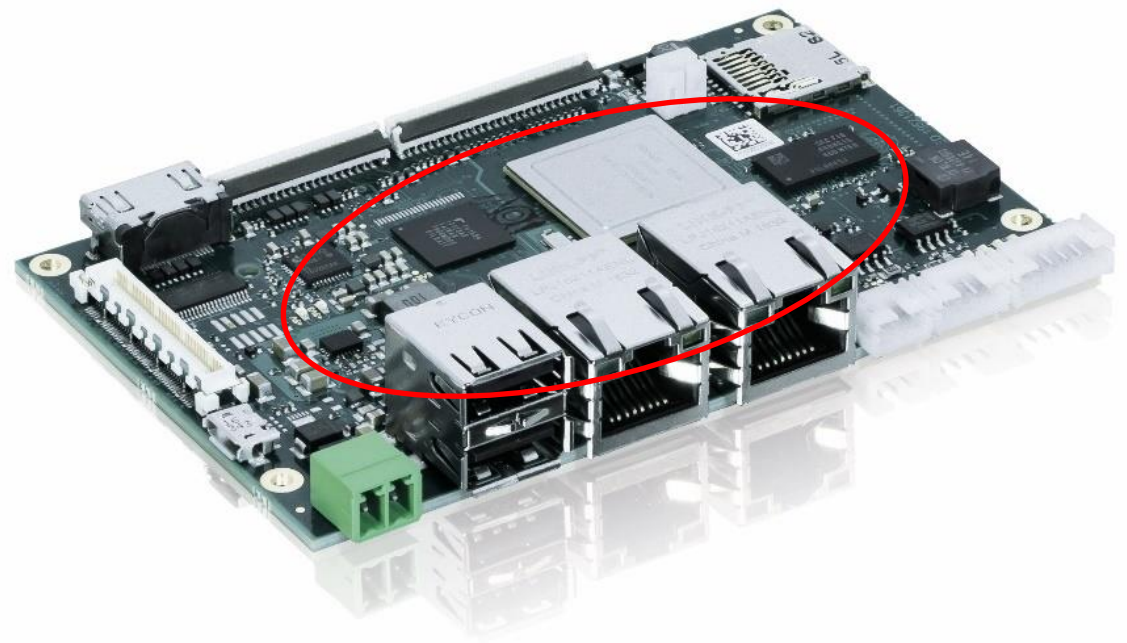
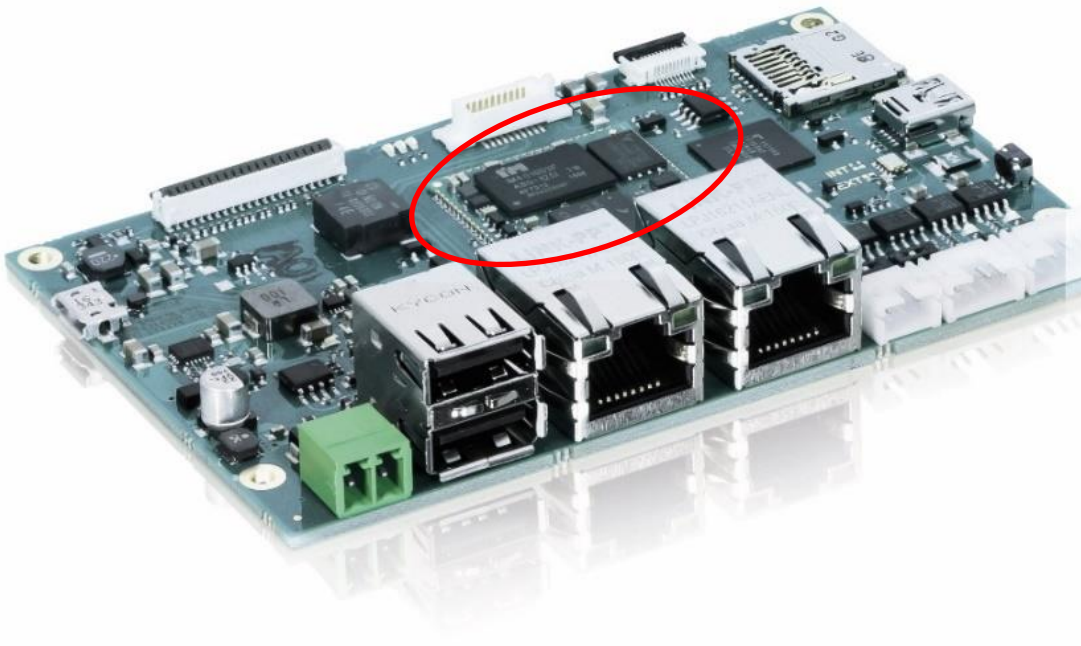
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MAIN GOALS FOR A „GOOD“ DEVELOPER OR PRODUCT MANAGER

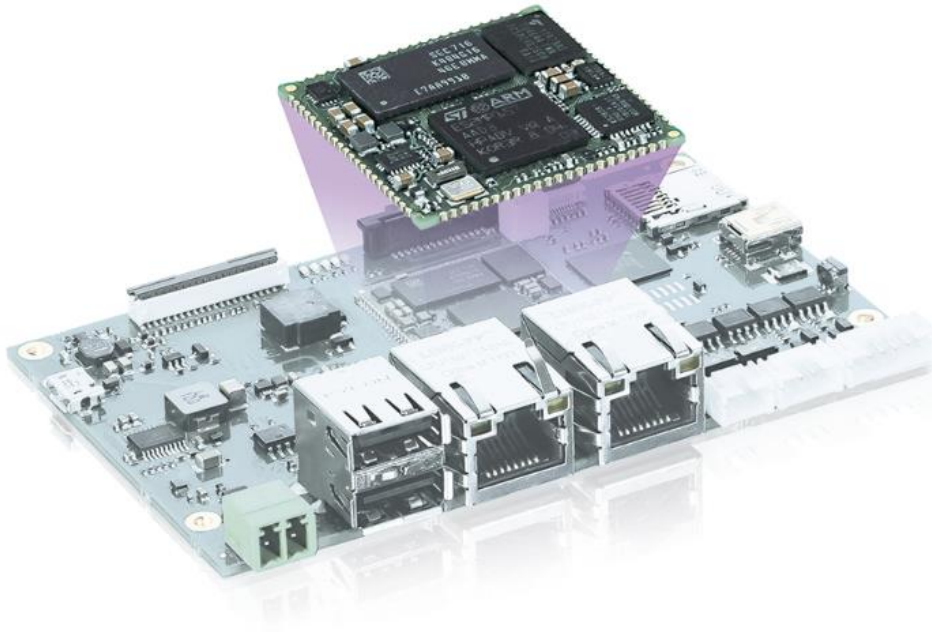


- Reduce effort (time and money)
- Reduce risk
- Reduce complexity
- Be fast
- Be flexible and prepared for future requirements (New Displays, Connectivity, IoT, ...)
- Be focused on your USP, your companies know how

LOOKING LIKE TWINS: SOM+BASEBOARD VERSUS SINGLE BOARD COMPUTER



A SOM IN A NUTSHELL



- ▶ Complete Core Hardware and Software
- ▶ μ P, GPU, Memory, Power supply, communication interfaces, GPIO
- ▶ Ready to use Software (SDK, Bootloader, OS, BSP, Drivers...)
- ▶ Independent of application
- ▶ Usable for the development of almost any product
- ▶ Combination of standardized SOM and application specific carrier board is a perfect platform for various embedded products

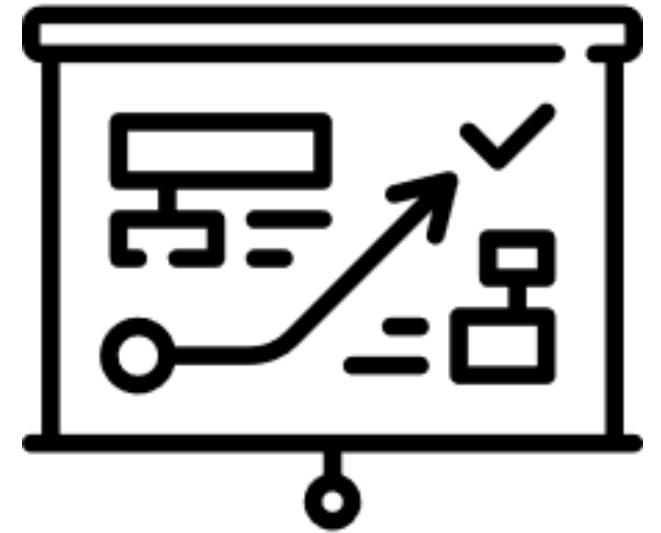
WHY DO WE HAVE SOMS NOWADAYS?



- ▶ Rapidly increasing requirements for small, powerful embedded systems (due to progressive digitization)
- ▶ First integration by semiconductor manufacturer in the form of SOCs
- ▶ Second integration by electronics manufacturer in the form of SOMs
- ▶ High number of connections on small space
- ▶ Critical Timings
- ▶ High quantity
- ▶ High quality

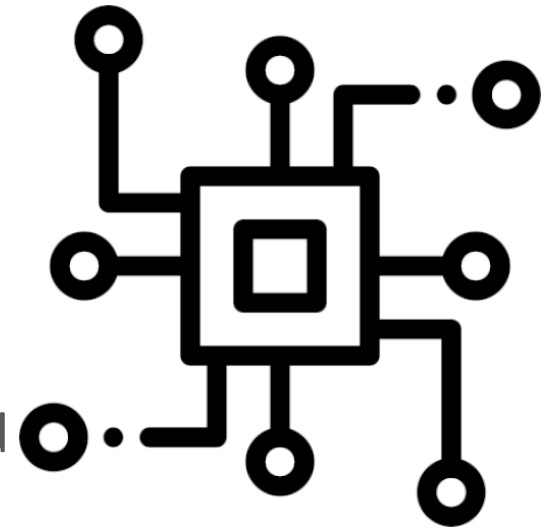
STRATEGIC ASPECTS

- ▶ Ready developed core module.
 - ▶ Shorter time to market
 - ▶ Less design risk due to well-tried solution
 - ▶ Long term available CPU module
 - ▶ Lifecycle management by manufacturer
- ▶ A CPU core optimized in every aspect
- ▶ Open X (Open Source, Open Hardware, Open Software)



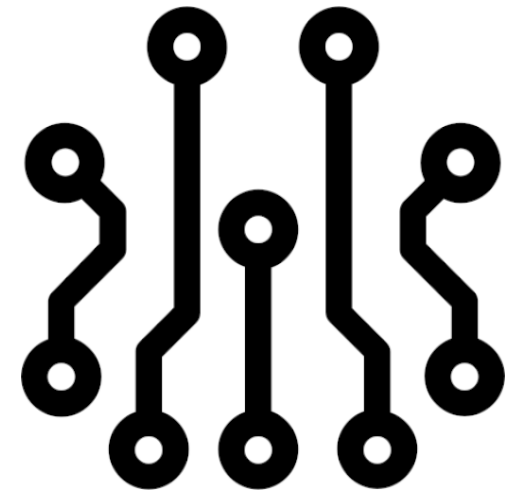
SCHEMATIC DESIGN ASPECTS

- ▼
 - ▶ Complex CPU Core is a ready developed module.
 - ▶ Usable as easy as a microcontroller
 - ▶ CPU Setup / Multiplexing
 - ▶ Power supply (Power up/down sequencing)
 - ▶ Memory design (DDR3/DDR4...)
 - ▶ Baseboard is application optimized
 - ▶ Exactly the required featureset, no overhead, design is BOM optimized
 - ▶ In-house standard connectors
 - ▶ It's your IP, it's your product



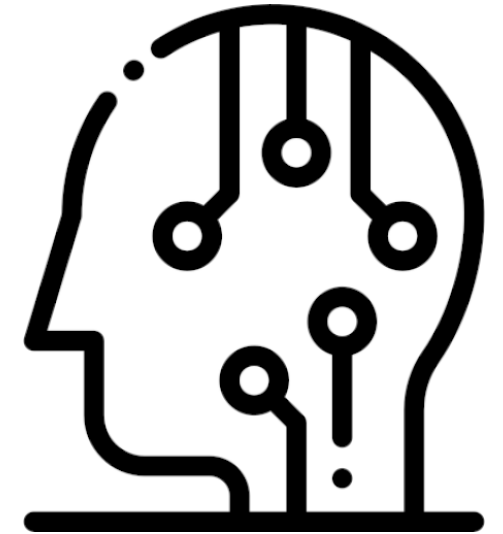
LAYOUT DESIGN ASPECTS

- ▶ You can use a ready developed module.
 - ▶ Complex DDR3/DDR4 RAM design is done
 - ▶ Length adjustments, Signal delay adjustments, RAM-Timing
 - ▶ High frequency design needed, optional simulation needed
 - ▶ Space needed for CPU core is defined right from the beginning
 - ▶ EMC is already checked
 - ▶ decoupling capacitors are placed (in right number and right position)
 - ▶ Impedance controlled lines are designed
- ▶ Placement according to environmental requirements



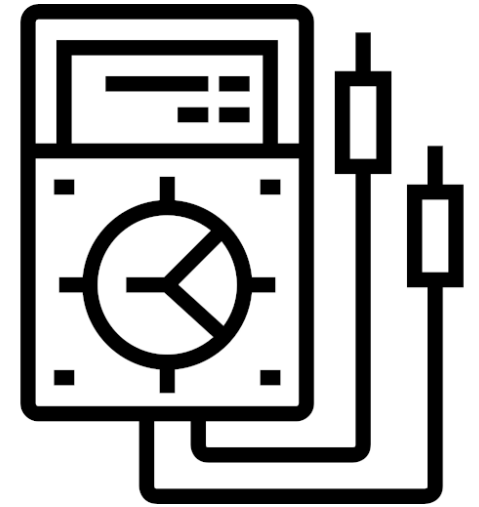
TECHNOLOGICAL ASPECTS

- ▶ Separation of normal and ultra-fine conductor structures (on baseboard and SOM)
- ▶ Separation of very small parts (0201) and bigger parts with thermal or mechanical requirements
 - ▶ (production machines / pcb requirements)
- ▶ Mechanical decoupling of sensitive components from stressed components (BGAs separated from connectors and sockets)



TESTING ASPECTS

- ▶ SOM can be tested individually
- ▶ SOM can be tested deeper and more intelligent in terms of accessible testing points
- ▶ Significant less testpoints needed on baseboard (lower cost for adapter)
- ▶ SOM can come preconfigured (Bootloader, OS, application, MAC address)
- ▶ Testing by a robot (fewer human errors)



HMI ASPECTS



- ▶ Generic graphics interfaces on SOM
- ▶ Converter to individual display on baseboard
- ▶ Family adapter concept
- ▶ Drivers and adaption for mainstream and individual displays
- ▶ GUI via QT
- ▶ Optimized Browser for Webterminal functionality

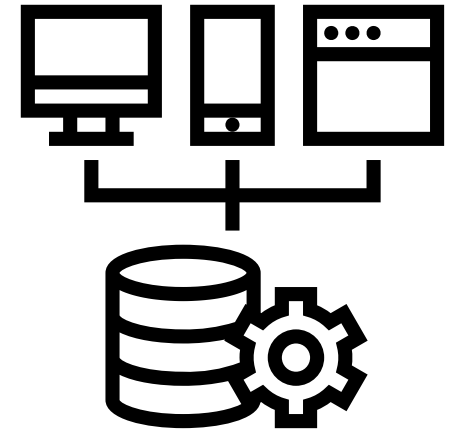


SOFTWARE ASPECTS

- ▶ Bootloader (Uboot)
- ▶ Linux BSP (Yocto based)
- ▶ Programming in C
- ▶ IEC 61131-3 PLC programming (CODESYS)
- ▶ GUI via QT
- ▶ Optimized Browser for Webterminal functionality
- ▶ Individual Software
- ▶ Support for individual components / drivers



CODESYS



COST ASPECTS

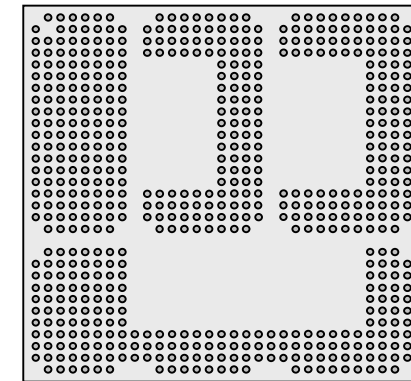
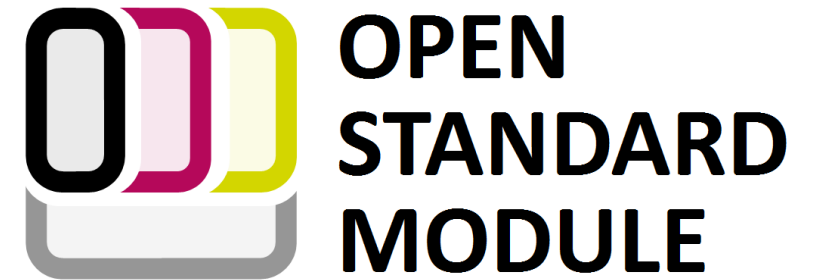


- ▶ Separation of the (small) 8 to 10 layer SOM and the (larger) 4 to 6 layer baseboard (lower PCB cost)
- ▶ Separation of normal and ultra-fine conductor structures (lower PCB cost, higher availability of PCB manufacturers)
- ▶ SOM cost optimized
- ▶ Benefit from higher quantities
- ▶ Baseboard BOM optimized
- ▶ SOM product maintenance free of charge



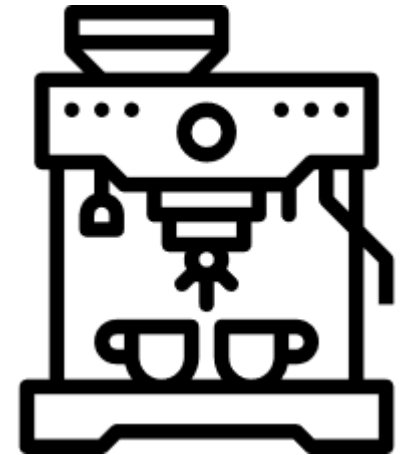
STANDARDIZATION

- ▶ OSM Standardization procedure startet in SGET
- ▶ 4 form factors: zero, small, medium, large
 - ▶ 30x13,5; 30x30; 30x48; 48x48 (mm)
- ▶ Predefined pinning
 - ▶ 147 pins, 267 pins, 395 pins, 593 pins (LGA)
- ▶ Broad range of manufacturers interested



SUMMARY OF ASPECTS

- ▶ Designing a system based on a modern, complex CPU is not a simple thing.
- ▶ Concentrate on your USP:
The scope and the features of your product are your USP.
The features, the functionality, the interfaces are placed on the baseboard.
- ▶ You get the schematic and the BOM of reference board (Open source hardware).
- ▶ You get the Linux BSP (Open source software).
- ▶ You can get design support (Review of schematic and layout).



UNLIMITED POSSIBILITIES



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#askTELEREX

#thankyouforlistening